

ABSTRACT

PHOTOSENSITIVE RESIN COMPOSITION

This invention provides a photosensitive resin composition and in particular, it provides a photosensitive resin composition comprising a) an acryl-based copolymer obtained by copolymerizing i) an unsaturated carbonic acid, unsaturated carbonic anhydride or mixture thereof, ii) a hydroxy group containing olefin-based unsaturated compound, and iii) an olefin-based unsaturated compound and then eliminating unreacted monomers; b) a 1,2-quinonediazide compound; c) an epoxy-based compound represented by any one of formula 1 to 6; and d) a solvent.

The photosensitive resin composition according to the invention has not only excellent performances in sensitivity, heat resistance, resolution, etc. but also remarkably improved transmission and preservation stability at room temperature so that it is suitable to form interlayer dielectrics during LCD manufacturing process.